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Around 1960

Can type package for transistors

~ Packaging ~

The package technology for transistors in the early stages around 1960 was introduced from the United States, in which a Ge transistor chip was soldered to a tab and the lead pins were soldered to the surface of the transistor chip with low melting point indium (In) solder material. And after soldering, it was coated with red lead (Pb3O4) resin to improve device reliability.

After the lead pin bonding, the tin-plated cap (Ne-Ni) was fitted to the stem by the tin-tin joining method and sealed, and it was called a can type transistor.

The transistors of this structure were used for portable small size transistor radios, replacing vacuum tube radios, and it became the basis of the development of the Japanese semiconductor industry.

